

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7250489

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUNSUKE KOGA	03/23/2022
TOMOKI SASAKI	03/23/2022
YOSHIE TACHIBANA	03/23/2022
SHUNSAKU YOSHIKAWA	03/23/2022
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23, SENJU-HASHIDO-CHO
City:	ADACHI-KU, TOKYO
State/Country:	JAPAN
Postal Code:	120-8555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17706965
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	434620-000293
NAME OF SUBMITTER:	JEFFREY L. COSTELLIA
SIGNATURE:	/Jeffrey L. Costellia, Reg. No. 35,483/
DATE SIGNED:	03/29/2022
Total Attachments: 4	
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Docket No. _____

ASSIGNMENT

WHEREAS, (I/we), (1)Shunsuke KOGA, (2)Tomoki SASAKI, (3)Yoshie TACHIBANA and
(4)Shunsaku YOSHIKAWA citizen of Japan, residing at (1) Tokyo, Japan,
(2) Tokyo, Japan, (3) Tokyo, Japan and (4) Tokyo, Japan
have invented a

PREFORM SOLDER AND METHOD OF MANUFACTURING THE SAME,
AND METHOD OF MANUFACTURING SOLDER JOINT

for which (I/we) have executed application papers for U.S. patent application filed herewith; and

WHEREAS, SENJU METAL INDUSTRY CO., LTD. having a place of business located
at 23, Senju-hashido-cho, Adachi-ku, Tokyo 120-8555 Japan, is desirous of acquiring the
exclusive right, title and interest in and to said invention and in and to the Letters Patent to be
granted and issued therefor in the United States of America and its territories and possessions,
and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby
acknowledged, (I/we), Shunsuke KOGA, Tomoki SASAKI, Yoshie TACHIBANA and
Shunsaku YOSHIKAWA do sell, assign, transfer and set over unto the said SENJU METAL
INDUSTRY CO., LTD., its successors and assigns, the full and exclusive right, title and interest
in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor,
not only for, to and in the United States of America, its territories and possessions, but also for,
to and in all other countries including all priority rights under the International Convention; and I
hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters
Patent to said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, in accordance
with this Assignment.

Docket No. _____

[ASSIGNMENT CONTINUATION]

Re: U.S. Patent Application entitled: PREFORM SOLDER AND METHOD OF MANUFACTURING THE SAME, AND METHOD OF MANUFACTURING SOLDER JOINT

Inventor: Shunsuke KOGA

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

23rd day of March, 2022.
(date) (month) (year)

Shunsuke Koga
Name: Shunsuke KOGA

Re: U.S. Patent Application entitled: PREFORM SOLDER AND METHOD OF MANUFACTURING THE SAME, AND METHOD OF MANUFACTURING SOLDER JOINT

Inventor: Tomoki SASAKI

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

23rd day of March, 2022.
(date) (month) (year)

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Docket No. _____

Tomoki SASAKI

Name: Tomoki SASAKI

Re: U.S. Patent Application entitled: PREFORM SOLDER AND METHOD OF MANUFACTURING
THE SAME, AND METHOD OF MANUFACTURING SOLDER
JOINT

Inventor: Yoshie TACHIBANA

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

23rd day of March, 2022
(date) (month) (year)

Yoshie TACHIBANA

Name: Yoshie TACHIBANA

Re: U.S. Patent Application entitled: PREFORM SOLDER AND METHOD OF MANUFACTURING
THE SAME, AND METHOD OF MANUFACTURING SOLDER
JOINT

Inventor: Shunsaku YOSHIKAWA

Docket No. _____

Tokyo, Japan

WITNESS MY HAND at _____, this
(city, state, country)

23rd day of March 2022
(date) (month) (year)

Shunsaku Yoshikawa

Name: Shunsaku YOSHIKAWA